Copper Layer Count: 2 Board Thickness: 1.6000 mm

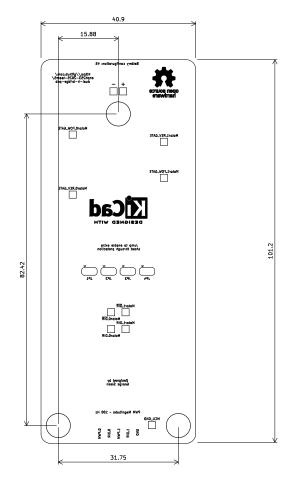
Board overall dimensions:  $40.8940 \text{ mm} \times 101.4730 \text{ mm}$ 

Min track/spacing: 0.1000 mm / 0.1000 mm Min hole diameter: 0.2500 mm

Copper Finish: None Impedance Control: No Castellated pads: No Plated Board Edge: No

Edge card connectors: No

Layer Name	Туре	Material	Thickness (mm)	Color	Epsilon R	Loss Tangent
F.Silkscreen	Top Silk Screen	Not specified	0 mm	Not specified	1	0
F.Paste	Top Solder Paste		0 mm		1	0
F.Mask	Top Solder Mask	Not specified	0.01 mm	Not specified	3.3	0
F.Cu	copper		0.035 mm		1	0
Dielectric	core	FR4	1.51 mm	Not specified	4.5	0.02
B.Cu	copper		0.035 mm		1	0
B.Mask	Bottom Solder Mask	Not specified	0.01 mm	Not specified	3.3	0
B.Paste	Bottom Solder Paste		0 mm		1	0
B.Silkscreen	Bottom Silk Screen	Not specified	0 mm	Not specified	1	0



George Sleen	
Team 5	
Sheet:	
File: dual-h-bridge.kicad_pcb	
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	litle: Dual H-Bridge				
Size: A4 Date: 2025-07-09		Date: 2025-07-09	Rev: v3.0.0		
	KiCad E.D.A. 9.0	.3	ld: 1/4		

Copper Layer Count: Board Thickness: 1.6000 mm

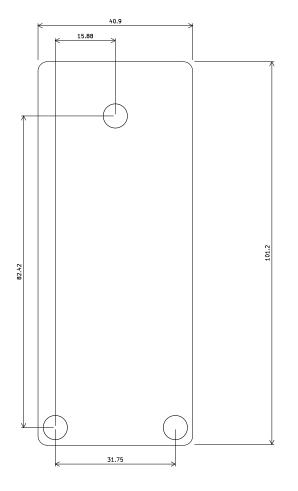
Board overall dimensions:  $40.8940 \text{ mm} \times 101.4730 \text{ mm}$ 

Min track/spacing: 0.1000 mm / 0.1000 mm Min hole diameter: 0.2500 mm

Copper Finish: None Impedance Control: No Plated Board Edge: No Castellated pads: No

Edge card connectors: Νo

Layer Name	Туре	Material	Thickness (mm)	Color	Epsilon R	Loss Tangent
F.Silkscreen	Top Silk Screen	Not specified	0 mm	Not specified	1	0
F.Paste	Top Solder Paste		0 mm		1	0
F.Mask	Top Solder Mask	Not specified	0.01 mm	Not specified	3.3	0
F.Cu	copper		0.035 mm		1	0
Dielectric	core	FR4	1.51 mm	Not specified	4.5	0.02
B.Cu	copper		0.035 mm		1	0
B.Mask	Bottom Solder Mask	Not specified	0.01 mm	Not specified	3.3	0
B.Paste	Bottom Solder Paste		0 mm		1	0
B.Silkscreen	Bottom Silk Screen	Not specified	0 mm	Not specified	1	0



Georg	е	Sleen
Team	5	

Sheet:

File: dual-h-bridge.kicad\_pcb

Title:	Dual	H	-Bi	rid	ge
			-		

Date: 2025-07-09 Rev: v3.0.0 Size: A4 KiCad E.D.A. 9.0.3 ld: 2/4

Copper Layer Count: 2 Board Thickness: 1.6000 mm

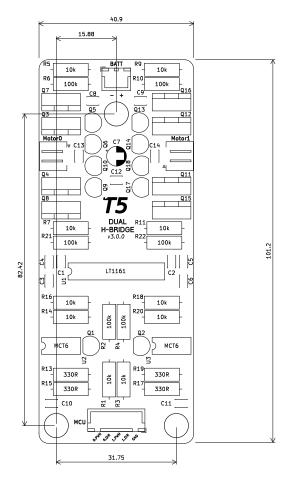
Board overall dimensions:  $40.8940 \text{ mm} \times 101.4730 \text{ mm}$ 

Min track/spacing: 0.1000 mm / 0.1000 mm Min hole diameter: 0.2500 mm

Copper Finish: None Impedance Control: No Castellated pads: No Plated Board Edge: No

Edge card connectors: No

Layer Name	Туре	Material	Thickness (mm)	Color	Epsilon R	Loss Tangent
F.Silkscreen	Top Silk Screen	Not specified	0 mm	Not specified	1	0
F.Paste	Top Solder Paste		0 mm		1	0
F.Mask	Top Solder Mask	Not specified	0.01 mm	Not specified	3.3	0
F.Cu	copper		0.035 mm		1	0
Dielectric	core	FR4	1.51 mm	Not specified	4.5	0.02
B.Cu	copper		0.035 mm		1	0
B.Mask	Bottom Solder Mask	Not specified	0.01 mm	Not specified	3.3	0
B.Paste	Bottom Solder Paste		0 mm		1	0
B.Silkscreen	Bottom Silk Screen	Not specified	0 mm	Not specified	1	0



George Sleen
Team 5
Sheet:
File: dual-h-bridge.kicad\_pcb

Title: Dual H-Bridge
Size: A4 Date: 2025-07-09 Rev: v3.0.0

Copper Layer Count: 2 Board Thickness: 1.6000 mm

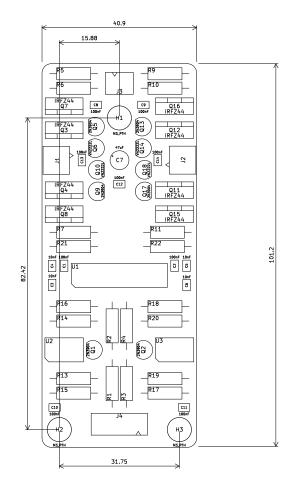
Board overall dimensions:  $40.8940 \text{ mm} \times 101.4730 \text{ mm}$ 

Min track/spacing: 0.1000 mm / 0.1000 mm Min hole diameter: 0.2500 mm

Copper Finish: None Impedance Control: No Castellated pads: No Plated Board Edge: No

Edge card connectors: No

Layer Name	Туре	Material	Thickness (mm)	Color	Epsilon R	Loss Tangent
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F.Cu	copper		0.035 mm		1	0
Dielectric	core	FR4	1.51 mm	Not specified	4.5	0.02
B.Cu	copper		0.035 mm		1	0
B.Mask	Bottom Solder Mask	Not specified	0.01 mm	Not specified	3.3	0
B.Paste	Bottom Solder Paste		0 mm		1	0
B.Silkscreen	Bottom Silk Screen	Not specified	0 mm	Not specified	1	0



George Slee	n	
Team 5		
Sheet: File: dual-h	ı—bridge.kicad_pcb	
Title: Dua	al H—Bridge	
Size: A4	Date: 2025-07-09	Rev: v3.0.0
KiCad F D A	9.0.3	Id: 4/4